

## 1.0A Synchronous Step-Down Converter

### Features

- 2.7V to 5.5V Input Voltage Range
- Input over voltage protection at 6V
- 40uA quiescent current in operation
- Output current up to 1A
- Efficiency up to 95%
- OCP, SCP and OTP protection
- SOT23-5L package

### Applications

- Set-top Box
- Solid State Drive
- WIFI and Network Devices
- Security surveillance system
- Toys
- TV
- All other electronic devices

### General Description

The AD3410K-06BT0 is a compact 5V Buck Converter which can deliver 1A output current.

AD3410K-06BT0 employs a proprietary control loop to achieve a fast transient load response. It keeps high converting efficiency in both light load and heavy load.

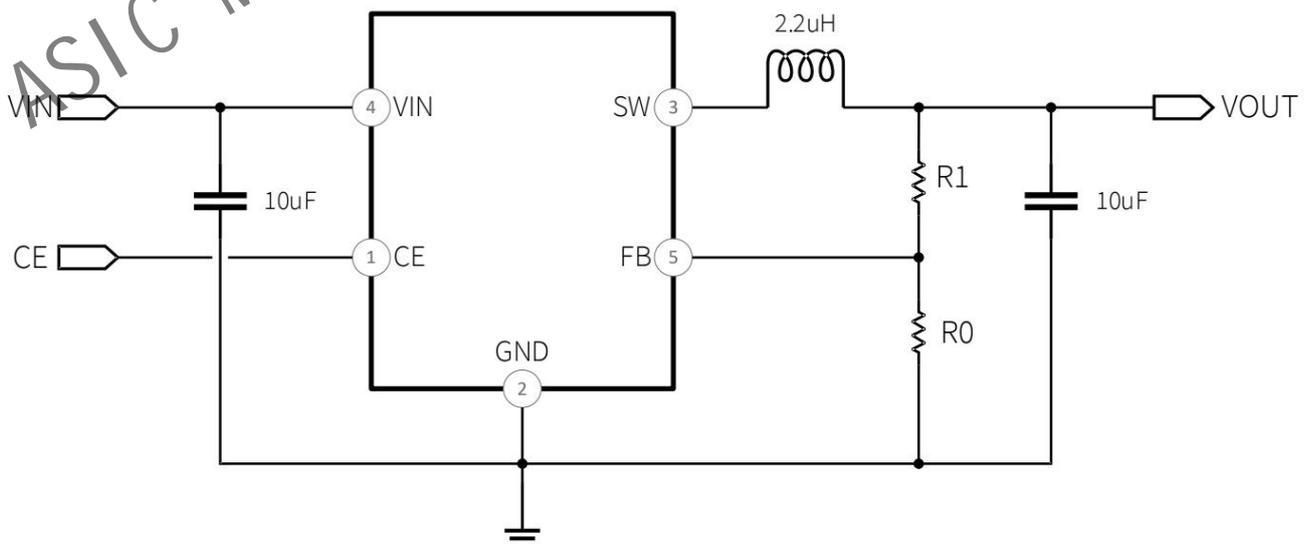
AD3410K-06BT0 is equipped with all kinds of protection, such as input over voltage protection, output short circuit

protection, over current protection and over temperature protection.

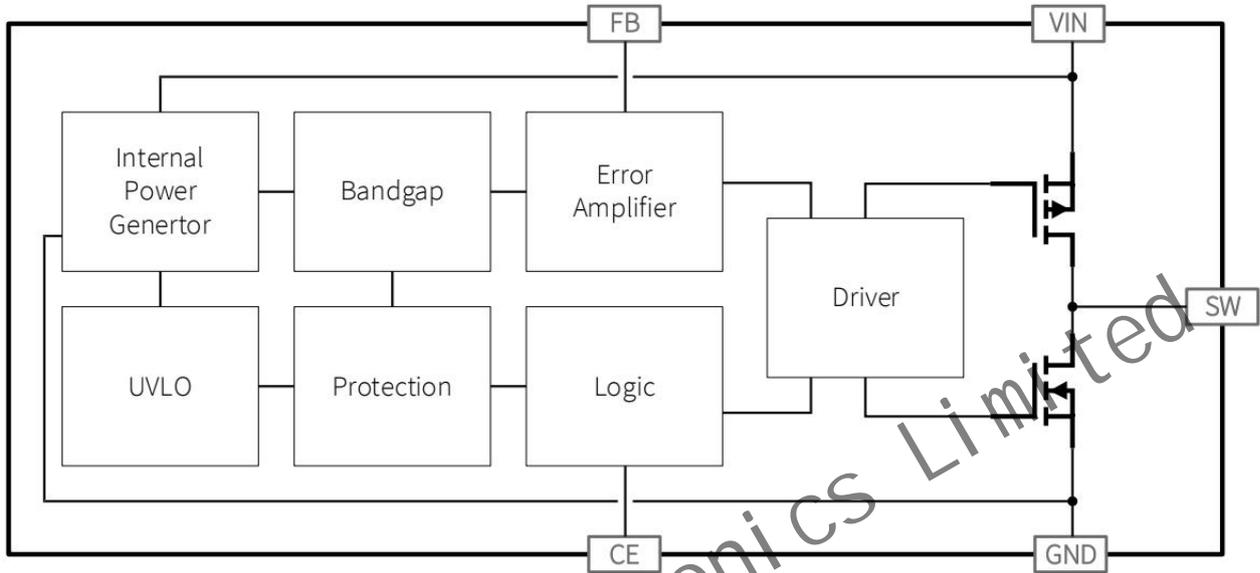
AD3410K-06BT0 consists of internal power tree generator, bandgap voltage reference module, under-voltage lockout (UVLO) module, error amplifier, protection circuitry, driver block, current sensing block and two power MOSFETs.

AD3410K-06BT0 is housed in a SOT23-5L package.

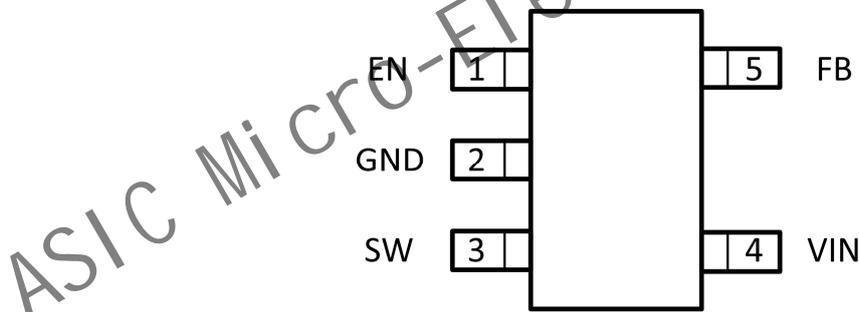
### Typical Application



## Block Diagram



## Package/order Information



(SOT23-5)

The package of AD3410K-06BT0 is SOT23-5L, with pin assignment shown in following table:

## Pin Description

PIN	NAME	FUNCTION
1	EN	Chip enable pin, pull high to turn on the chip.
2	GND	Ground Pin
3	SW	The switching node, connecting a 2.2uH inductor to this node
4	VIN	The input power node, connecting a 10uF capacitor to ground.
5	FB	Feedback node, with Vfb at 0.6V

**Absolute Maximum Ratings**

Item	Min	Max	Unit
V <sub>IN</sub> voltage <sup>(1)</sup>	-0.3	6.0	V
V <sub>OUT</sub> voltage <sup>(1)</sup>	-0.3	5.5	V
Continuous Power Dissipation (TA = 25°C) <sup>(2)</sup>			
Power dissipation	Internally Limited		
Operating junction temperature, T <sub>J</sub>	-40	125	°C
Storage temperature, T <sub>stg</sub>	-65	150	°C
Lead Temperature (Soldering, 10sec.)		260	°C

Symbol	Parameter	Max.	Unit
θ <sub>JA</sub>	Thermal Resistance <sup>(3)</sup>	170	°C/W
θ <sub>JC</sub>		75	°C/W

Note (1): Exceeding these ratings may damage the device.

Note (2): The maximum allowable power dissipation is a function of the maximum junction temperature T<sub>J(MAX)</sub>, the junction-toambient thermal resistance θ<sub>JA</sub>, and the ambient temperature T<sub>A</sub>. The maximum allowable continuous power dissipation at any ambient temperature is calculated by PD(MAX)=(T<sub>J(MAX)</sub>-T<sub>A</sub>)/θ<sub>JA</sub>. Exceeding the maximum allowable power dissipation will cause excessive die temperature, and the regulator will go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.

Note (3): Measured on JESD51-7, 4-layer PCB.

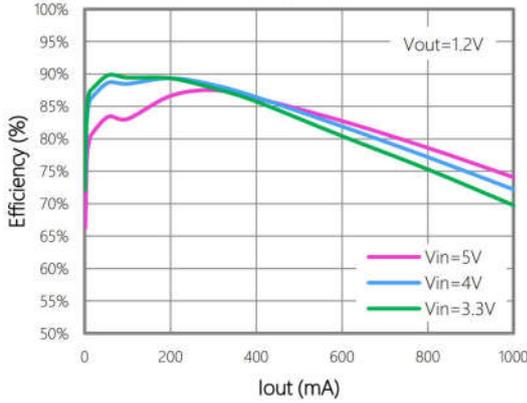
**Electrical Characteristics**
 $V_{IN}=5V$ ,  $T_A=25^{\circ}C$ , unless otherwise specified.

Parameter	Conditions	Min.	Typ.	Max.	Unit
Input Voltage Range		2.7		5.5	V
Input over voltage protection		5.8	6	6.5	V
Quiescent current, $I_Q$	$V_{IN}=5.0V$	20	40	60	$\mu A$
Shutdown current, $I_{OFF}$	$V_{IN}=5.0V$ , $V_{CE}=0$		0.	2.0	$\mu A$
Input voltage UVLO	Rising		2.55	2.65	V
	Falling	2.25	2.37		V
Feedback Voltage	$V_{IN}=5.0V$	0.588	0.6	0.612	V
Output current Limit	$V_{IN}=5.0V$ , $V_{OUT}=3.3V$	1	1.2		A
Line regulation	$V_{IN}=3$ to $5.0V$		0.2		%/V
Load regulation	$I_{OUT}=0.1 - 1A$		0.1	2	%/A
Switching frequency	$V_{IN}=5.0V$	1	1.5	2	MHz
ON resistance PMOS	$V_{IN}=5.0V$		0.38		$\Omega$
ON resistance NMOS	$V_{IN}=5.0V$		0.25		$\Omega$
CE input threshold ON	$V_{IN}=5.0V$		0.9	1.1	V
CE input threshold OFF	$V_{IN}=5.0V$	0.4	0.7		V
CE input pull down resistor			750		k $\Omega$
Output discharge resistor, $R_{pd}$	$V_{IN}=5.0V$		600		$\Omega$
Over temperature protection			150		$^{\circ}C$
OTP hysteresis			40		$^{\circ}C$

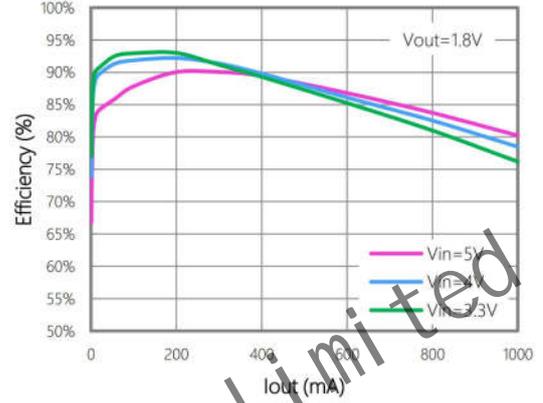
**Typical Performance Characteristics**

CIN=COUT=10uF, TA = 25°C, unless otherwise specified.

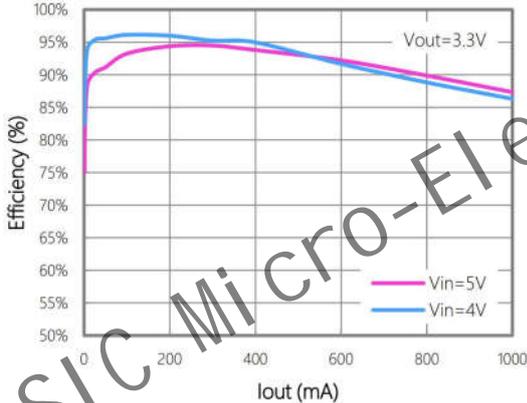
**Efficiency vs. Iout**



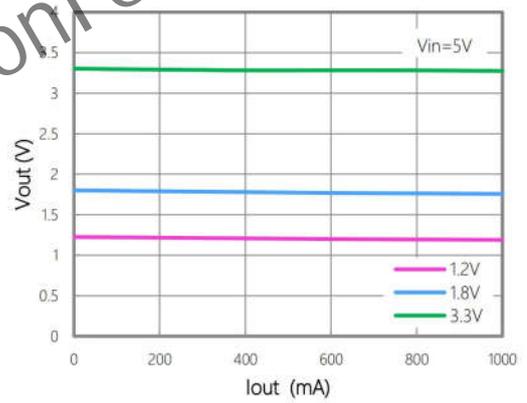
**Efficiency vs. Iout**



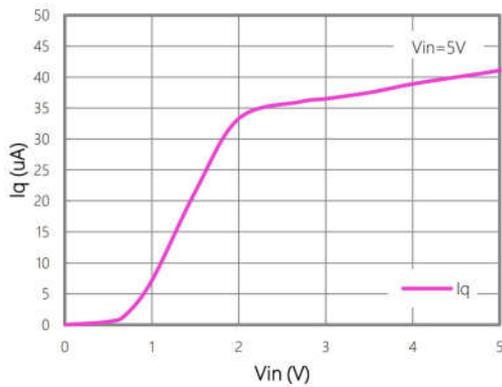
**Efficiency vs. Iout**



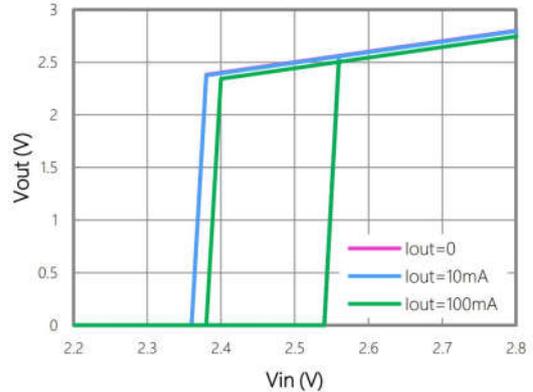
**Vout vs. Iout**



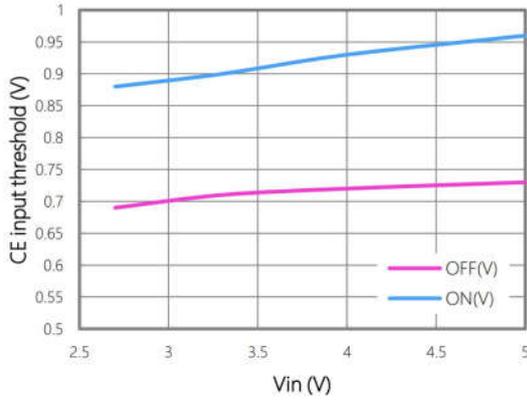
**Iq vs. Vin**



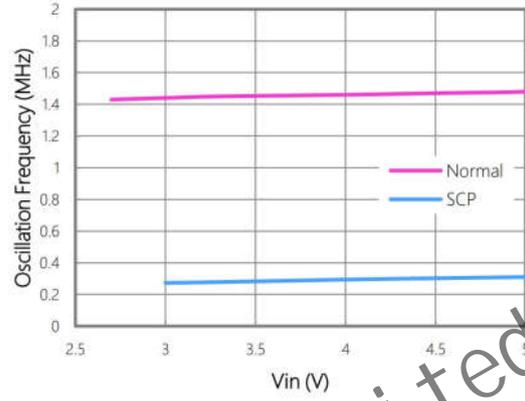
**UVLO vs. Vin**



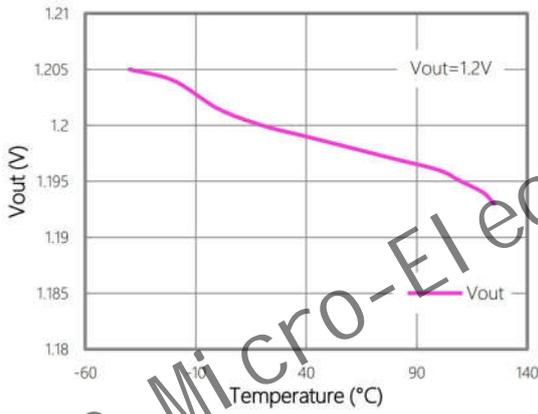
Threshold vs. Vin



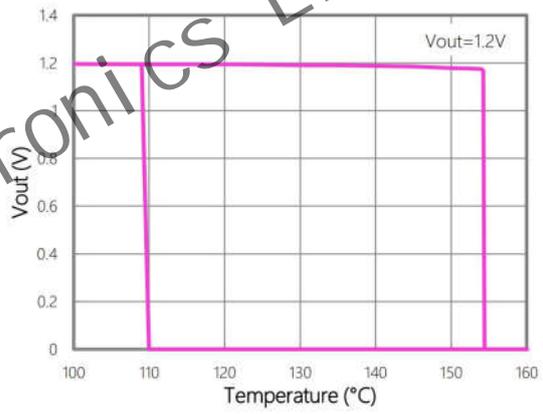
Frequency vs. Vin



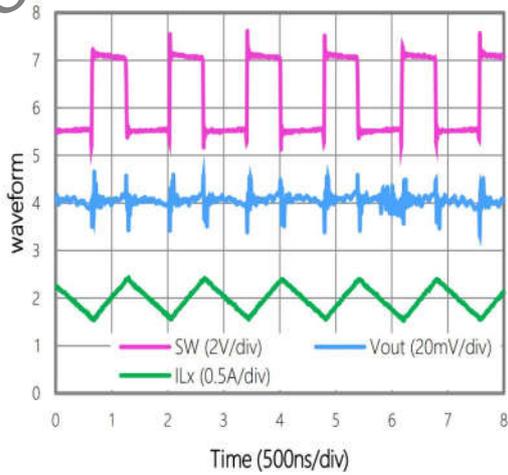
Vout vs. Temp



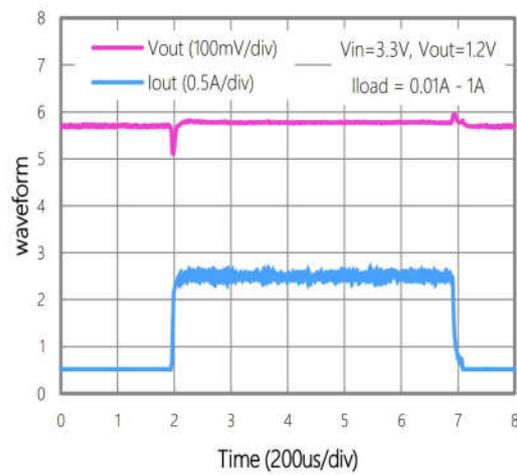
OTP Hysteresis

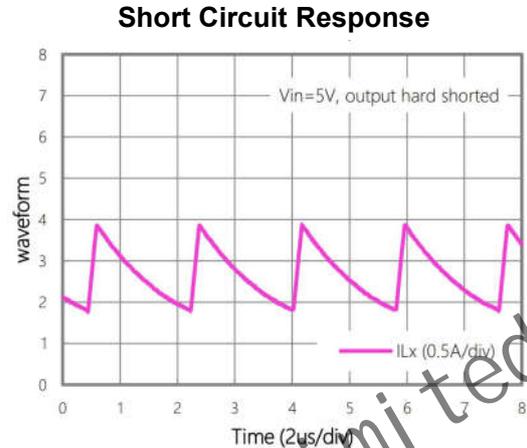
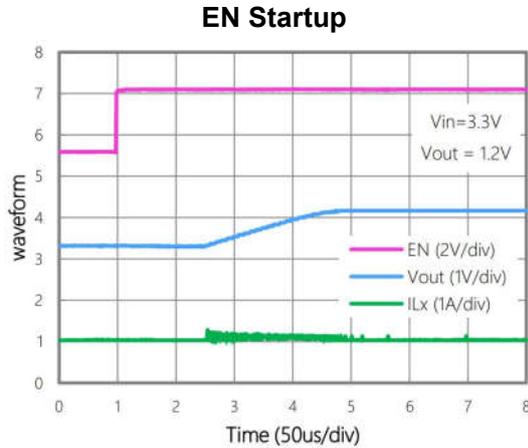


Switching Waveform



Load Transient Response





## Applications Information

### Output Voltage Setting

AD3410K-06BT0's feedback voltage is set at 0.6V, and it requires a resistor from FB node to ground, named R0, which is suggested to be less than 120K. Assuming the resistor between output node and FVB node is R1, the output voltage of DC-DC converting system is given by:

$$V_{out} = \frac{0.6V}{R_0} \times (R_1 + R_0)$$

### Capacitor Selection

AD3410K-06BT0 requires one minimal 10μF MLCC capacitor at VIN node and one 10μF MLCC capacitor at VOUT node, however, it is always recommended to have two 10μF MLCC capacitors placed in parallel both at VIN and VOUT node to minimize the noise and withstand the current surge. It is also essential to place both input capacitors and output capacitors as close to AD3410K-06BT0's VIN pin and VOUT pin as possible. An PCB layout example is shown at PCB layout recommendation section.

### Inductor Selection

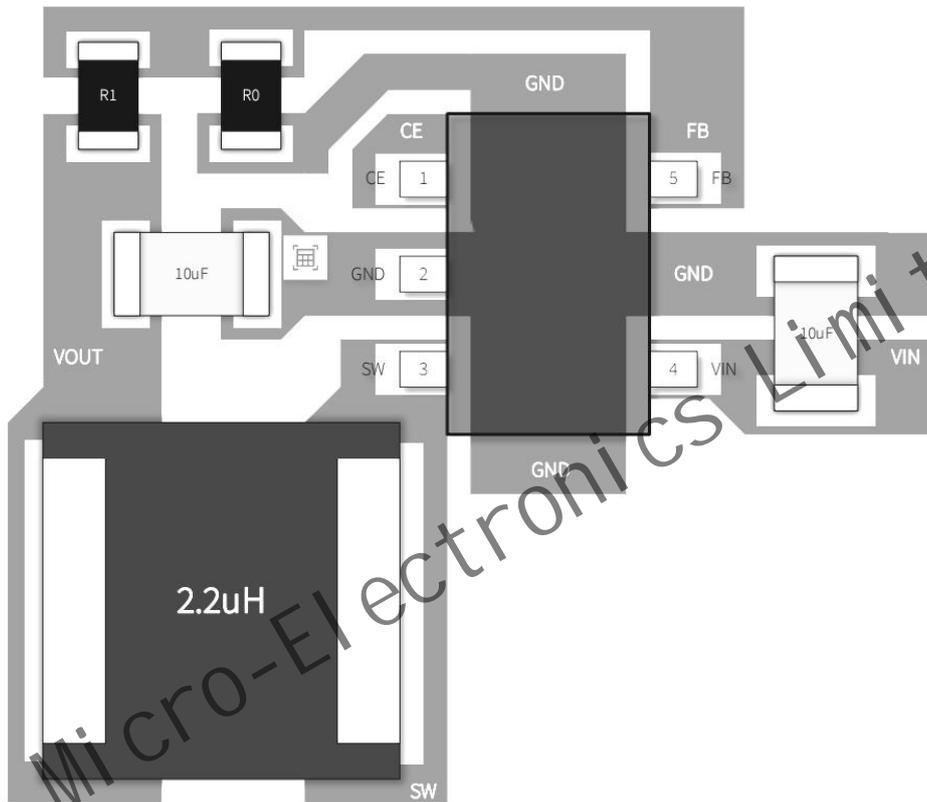
AD3410K-06BT0 works at a 1.5MHz oscillating frequency which helps to have a small voltage ripple at output. And 2.2μH inductor is found the most suitable value while meeting requirements on small output voltage ripple as well as a high-power conversion efficiency.

### Thermal Considerations

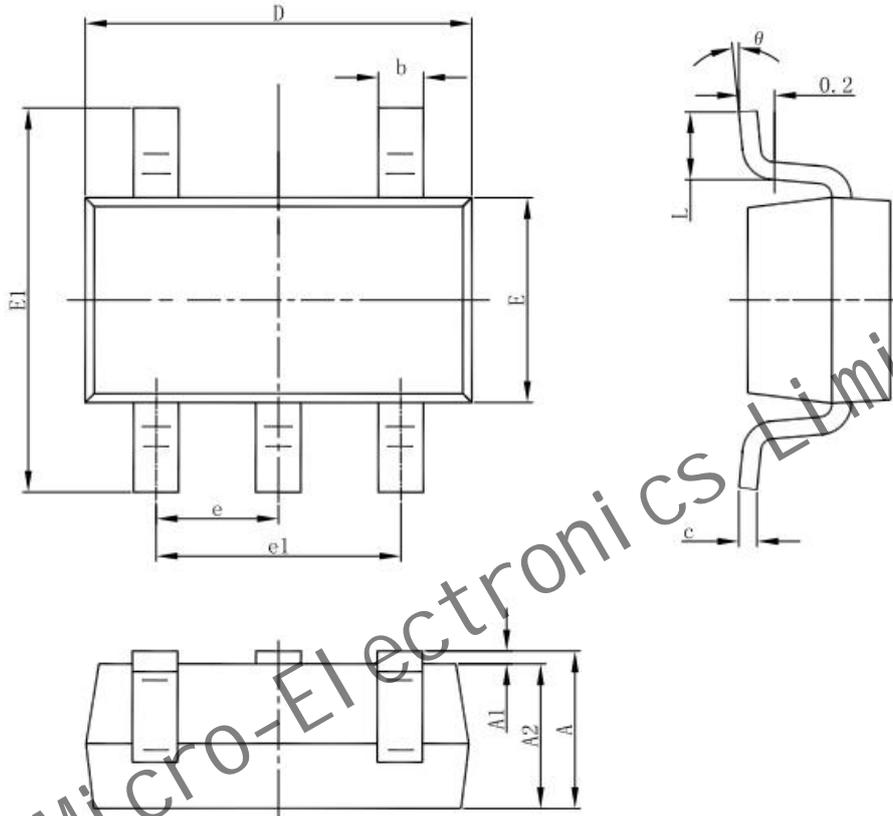
Though AD3410K-06BT0 is a high efficiency DC/DC converter, there will always be some power lost during conversion, most of which becomes heat to make junction temperature higher. PCB design to ensure a good heat dissipation is important. Because the heat dissipation of the SOT23-5L package is conducted through the pin No. 2, which is GND node of AD3410K-06BT0, please make sure the ground plate of PCB is big enough to carry away the heat generated in the chip.

**PCB Layout**

An illustration of PCB layout recommendation with key elements is laid out as following. Please follow this PCB instruction to place the key peripheral devices such as input capacitors, output capacitors and inductor. And star-like connection for ground node is essential. And keeping power loop area as small as possible will improve the EMI performance.



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**Package Description**  
**SOT23-5 Outline Dimensions**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
theta	0°	8°	0°	8°

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